



April 22, 1999

6p 2811
HIDS
Lewis
6.28.99

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/249,252 02/12/99

M.S. Lin

RECEIVED

STRAIN RELEASE CONTACT SYSTEM FOR
INTEGRATED CIRCUITS

APR 29 1999

Grp. Art Unit: 2811

TECHNOLOGY CENTER 2800

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

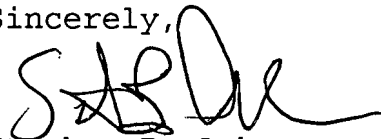
The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

U.S. Patent 5,831,331 to Lee, "Self-Shielding Inductor for
Multilayer Semiconductor Integrated Circuits", describes an
inductive structure for an integrated circuit. The inductor
has a first turn that shields the other turns of the inductor
from a proximate ground plane. Multiple turns are disposed one
above another in respective metalization layers of the
integrated circuit.

U.S. Patent 5,663,596 to Little, "Integrated Circuits Spring Contacts", describes an integrated-circuit interconnect which can be formed at the wafer level which is achieved by depositing an intentionally stressed contact layer over a release layer which is subsequently removed.

U.S. Patent 5,665,648 to Little, "Integrated Circuit Spring Contact Fabrication Methods", discloses chip contacting pads which are located on the vertical edges of the integrated circuit chip. It is attached to a substrate through spring contacts that have a base portion joined to a line on the substrate and a spring portion that presses against the edge of the chip. To fabricate the spring, a release layer is first laid down. Then a metal film is deposited under conditions known to induce high tensile stress so that, when the release layer is etched away, the freed metal curls up to a sufficient degree to allow the chip to be pushed against its underside, thereby forming a spring contact.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', with a long horizontal flourish extending to the right.

Stephen B. Ackerman,
Reg. No. 37661